

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT7169198

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HONGPO GAO	09/21/2017
REE LEI	09/21/2017
HUADONG LI	09/21/2017
WAYNE LI	09/21/2017
JIBING DONG	09/21/2017
SHAOQIN GONG	09/21/2017
RECEIVING PARTY DATA	
Name:	EMC IP HOLDING COMPANY LLC
Street Address:	176 SOUTH STREET
City:	HOPKINTON
State/Country:	MASSACHUSETTS
Postal Code:	01748
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16842242
CORRESPONDENCE DATA	
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Correspondent Name:	BAINWOOD, HUANG & ASSOCIATES, LLC
Address Line 1:	2 CONNECTOR ROAD
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ATTORNEY DOCKET NUMBER:	1003-825.001
NAME OF SUBMITTER:	BRUCE D. RUBENSTEIN, ESQ.
SIGNATURE:	/Bruce D. Rubenstein #39,349/
DATE SIGNED:	02/10/2022
Total Attachments: 8	

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ASSIGNMENT

WHEREAS, we, Hongpo Gao, Ree Sun, Huadong Li, Wayne Li, Jibing Dong and Shaoqin Gong have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled ***METHOD OF MANAGING REDUNDANT ARRAY OF INDEPENDENT DISKS AND ELECTRONIC DEVICE*** (Application), the specification of which:

- is being executed on even date herewith and is about to be filed in the United States Patent Office;
- was filed on September 20, 2017 as U.S. Application No. 15/710,809;
- was patented under U.S. Patent No. _____ on _____.

WHEREAS, EMC IP Holding Company LLC (hereinafter "ASSIGNEE"), a limited liability company organized and existing under the laws of the State of Delaware and having a usual place of business at 176 South Street, Hopkinton, Massachusetts 01748 desires to acquire an interest therein in accordance with agreements duly entered into with us;

NOW, THEREFORE, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by us had this assignment and sale not been made; we hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. We hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

AND, we hereby further agree for ourselves and our executors and administrators to execute upon request any other lawful documents and likewise to perform any other lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution,

reissue, divisional or continuation applications and preliminary or other statements and the giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

AND, we do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives;

AND, we hereby authorize our attorneys, EMC IP Holding Company LLC, to insert here in parenthesis (15/710,809 filed September 20, 2017) the application number and filing date of said Application (or foreign counterpart application) to facilitate the recording or other official processing of this Assignment.

IN TESTIMONY WHEREOF, we have hereunto set our hands and affixed our seals as set forth below:

Date: 2017.9.21

Hongpo Gao
Inventor's Signature

Full Name: **Hongpo Gao**
Residence: Tsinghua Science Park
Beijing, CN 100084
Citizenship: CN
Mailing Address: Same as above

I, Xu Tao (name of first witness), whose residential address is 8/F, Block D, Tsinghua Science Park, No.1 Zhongguamen East Road Haidian District was personally present and did see Hongpo Gao (name of person signing the assignment), who is personally known to me, execute the above assignment.

Xu Tao (signature of first witness)
Signed at Same as above (location of witness signature)
on this day, Sept. 21, 20 17 (date of signature).

I, Baote Zhuo (name of second witness), whose residential address is 7/F, Block D, Tsinghua Science Park, Haidian District, Beijing P.R.C was personally present and did see Hongpo Gao (name of person signing the assignment), who is personally known to me, execute the above assignment.

Baote Zhuo (signature of second witness)
Signed at 7/F, Block D, Tsinghua Science Park, Haidian District, Beijing, P.R.C (location of witness signature)
on this day, 09.22, 20 17 (date of signature).

Date: 2017. 9. 21

Sun Lei
Inventor's Signature

Full Name: **Ree Lei**
Residence: 9-1-301, GuoFengMeiTang
Beijing, CN
Citizenship: CN
Mailing Address: Same as above

I, Xu Tao (name of first witness), whose residential address is 8/F, Block D, Tsinghua Science Park, No. 1 Zhongguancun East Road, Haidian District was personally present and did see Ree Lei (name of person signing the assignment), who is personally known to me, execute the above assignment.

Xu Tao (signature of first witness)
Signed at same as above (location of witness signature)
on this day, Sept, 21, 2017 (date of signature).

I, Baote Zhuo (name of second witness), whose residential address is 8/F, Block D, Tsinghua Science Park, Haidian District Beijing, P.R.C was personally present and did see Ree Lei (name of person signing the assignment), who is personally known to me, execute the above assignment.

Baote Zhuo (signature of second witness)
Signed at 8/F, Block D, Tsinghua Science Park, Haidian District Beijing, P.R.C (location of witness signature)
on this day, 09. 22, 2017 (date of signature).

Date: 2017.9.21

Huadong Li
Inventor's Signature

Full Name: **Huadong Li**
Residence: No. 26 Shenggubeili, Apt. 2-014
Beijing, CN 100083
Citizenship: CN
Mailing Address: Same as above

I, Xu Tao (name of first witness), whose residential address is 8/F, Block D, Tsinghua Science Park, No.1 Zhongyuan East Road, Haidian District was personally present and did see Huadong Li (name of person signing the assignment), who is personally known to me, execute the above assignment.

Xu Tao (signature of first witness)
Signed at same as above (location of witness signature)
on this day, sept 21, 20 17 (date of signature).

I, Baote Zhuo (name of second witness), whose residential address is 2/F, Block D, Tsinghua Science Park, Haidian District, Beijing P.R.C was personally present and did see Huadong Li (name of person signing the assignment), who is personally known to me, execute the above assignment.

Baote Zhuo (signature of second witness)
Signed at 2/F, Block D, Tsinghua science park, Haidian District, Beijing P.R.C (location of witness signature)
on this day, 09.22, 20 17 (date of signature).

Date: 2017/9/21

Wayne Li
Inventor's Signature

Full Name: **Wayne Li**
Residence: Tsinghua Science Park
No.1 Zhongguancun East Road
Beijing, CN 100084
Citizenship: CN
Mailing Address: Same as above

I, Xu Tao (name of first witness), whose residential address is
8/F, Block D, Tsinghua Science Park, No.1 Zhongguancun East Road, Haidian District
was personally present and did see Wayne Li (name of person signing the assignment), who is
personally known to me, execute the above assignment.

Xu Tao (signature of first witness)
Signed at Same as above (location of witness signature)
on this day, Sept. 21, 2017 (date of signature).

I, Baote Zhuo (name of second witness), whose residential address is
7/F, Block D, Tsinghua Science Park, Haidian District, Beijing, P.R.C
was personally present and did see Wayne Li (name of person signing the assignment), who is
personally known to me, execute the above assignment.

Baote Zhuo (signature of second witness)
Signed at 7/F, Block D, Tsinghua Science Park, Haidian District, Beijing, P.R.C (location of witness signature)
on this day, 09. 22, 2017 (date of signature).

Date: 2017/9/21

Jibing Dong
Inventor's Signature

Full Name: **Jibing Dong**
Residence: 7/F, Block D, Tsinghua Science
Beijing, CN
Citizenship: CN
Mailing Address: Same as above

I, Xu Tao (name of first witness), whose residential address is 8/F, Block D, Tsinghua Science Park, No. 1 Zhongguancun East Road, Haidian District was personally present and did see Jibing Dong (name of person signing the assignment), who is personally known to me, execute the above assignment.

Xu Tao (signature of first witness)
Signed at same as above (location of witness signature)
on this day, Sept, 21, 2017 (date of signature).

I, Baote Zhuo (name of second witness), whose residential address is 7/F, Block D, Tsinghua Science Park, Haidian District, Beijing, P.R.C. was personally present and did see Jibing Dong (name of person signing the assignment), who is personally known to me, execute the above assignment.

Baote Zhuo (signature of second witness)
Signed at 7/F, Block D, Tsinghua Science Park, Haidian District, Beijing, P.R.C. (location of witness signature)
on this day, 09, 22, 2017 (date of signature).

Date: 2017.9.21

Shaoqin Gong
Inventor's Signature

Full Name: **Shaoqin Gong**
Residence: No.29, Chengfu Road, Haidian District
Beijing, CN
Citizenship: CN
Mailing Address: Same as above

I, Xu Tao (name of first witness), whose residential address is
8/F, Block D, Tsinghua Science Park, No.1 Zhonggucun East Road Haidian District
was personally present and did see Shaoqin Gong (name of person signing the assignment), who
is personally known to me, execute the above assignment.

Xu Tao (signature of first witness)
Signed at Same as above (location of witness signature)
on this day, Sept. 21, 2017 (date of signature).

I, Baote Zhuo (name of second witness), whose residential address is
7/F, Block D, Tsinghua Science park Haidian District, Beijing, P.R.C
was personally present and did see Shaoqin Gong (name of person signing the assignment), who
is personally known to me, execute the above assignment.

Baote Zhuo (signature of second witness)
Signed at 7/F, Block D, Tsinghua Science park Haidian District, Beijing, P.R.C (location of witness signature)
on this day, 09.22, 2017 (date of signature).